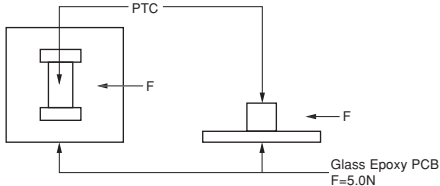


■ PRG18/21BC Series

| No. | Item | Rating Value | Method of Examination | | | | | | | | | | | | | | | |
|------|----------------------------|---|--|------|------------|-------------|---|------------|----|---|------------|-------|---|------------|----|---|------------|-------|
| 1 | Operating Temp. | -10 to 60°C | Temperature range with maximum voltage applied to PTC. | | | | | | | | | | | | | | | |
| 2 | Resistance Value (at 25°C) | The resistance value should be within the specified tolerance. | After leaving for 24 hrs. or more in 25°C, it measures by 4 wire measuring methods using the direct-current terminal current of 10mA or less (0.1 or less Vdcs). | | | | | | | | | | | | | | | |
| 3 | Withstanding Voltage | Without damage | We apply 120% of the maximum operating voltage to PTC by raising gradually for 180±5 secs. at 25°C. (A protective resistor is to be connected in series, and the inrush current through PTC must be limited below maximum rated value.) | | | | | | | | | | | | | | | |
| 4 | Adhesive Strength | There is no sign of exfoliation on electrode. | <p>EIAJ ET-7403 term 9 Soldered PTC to PCB and add a force of 5.0N in the direction as shown below.</p>  <p style="text-align: right;">Glass Epoxy PCB F=5.0N</p> | | | | | | | | | | | | | | | |
| 5 | Vibration | Normal appearance Resistance change: not to exceed ±20% (*) | <p>JIS C 5102 term 8.2 Soldered PTC to PCB Vibration: A 10-55-10Hz (1 min.) Width: 1.5mm Vibrate for 2 hrs. in each of 3 mutually perpendicular planes for a total of 6 hrs.</p> | | | | | | | | | | | | | | | |
| 6 | Solderability | Min. 75% electrode is covered with new solder. Resistance change: not to exceed ±20% (*) | <p>JIS C 5102 term 8.4 Solder: Sn-3Ag-0.5Cu Solder temp: 245±5°C Soaking time: 3±0.5 secs. Soaking position: Until a whole electrode is soaked.</p> | | | | | | | | | | | | | | | |
| 7 | Soldering Heat Resistance | Normal appearance Resistance change: not to exceed ±20% (*) | <p>Solder: Sn-3Ag-0.5Cu Flux: Solder paste containing less than 0.2wt% of chlorine. Preheating: 150±5°C 3 mins. Peak temp.: 260±5°C 10±5 secs. (reflow) PCB: Glass Epoxy PCB (JIS C 6484)</p> | | | | | | | | | | | | | | | |
| 8 | Dry Heat | | 60±3°C leave for 1000±12 hrs. | | | | | | | | | | | | | | | |
| 9 | Cold | | -10±3°C leave for 1000±12 hrs. | | | | | | | | | | | | | | | |
| 10 | Damp Heat | | 60±2°C, 90-95%RH leave for 500±4 hrs. | | | | | | | | | | | | | | | |
| 11 | Temperature Cycling | Normal appearance Resistance change: not to exceed ±20% (*) | <p>JIS C 5102 term 9.3 Times: 5 cycles</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th>Step</th> <th>Temp. (°C)</th> <th>Time (min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-20 +0, -3</td> <td>30</td> </tr> <tr> <td>2</td> <td>Room temp.</td> <td>10-15</td> </tr> <tr> <td>3</td> <td>+85 +3, -0</td> <td>30</td> </tr> <tr> <td>4</td> <td>Room temp.</td> <td>10-15</td> </tr> </tbody> </table> | Step | Temp. (°C) | Time (min.) | 1 | -20 +0, -3 | 30 | 2 | Room temp. | 10-15 | 3 | +85 +3, -0 | 30 | 4 | Room temp. | 10-15 |
| Step | Temp. (°C) | Time (min.) | | | | | | | | | | | | | | | | |
| 1 | -20 +0, -3 | 30 | | | | | | | | | | | | | | | | |
| 2 | Room temp. | 10-15 | | | | | | | | | | | | | | | | |
| 3 | +85 +3, -0 | 30 | | | | | | | | | | | | | | | | |
| 4 | Room temp. | 10-15 | | | | | | | | | | | | | | | | |
| 12 | High Temperature Load | | 60±3°C (in air), PTC is applied maximum operating voltage for 1.5 hrs. on and 0.5 hrs. off. This cycle is repeated for 500±10 hrs. | | | | | | | | | | | | | | | |

(*) The resistance measurement after the test.

After leaving for 24 hours or more in 25±2°C, it measures by 4 wire measuring methods using the direct-current terminal current of 10mA or less (0.1 or less Vdcs).

Above mentioned soldering in "4. Adhesive Strength" and "5. Vibration" is done under the following conditions at our site.

- Glass-Epoxy PC board
- Standard land dimension
- Standard solder paste
- Standard solder profile

Above conditions are mentioned in Notice.

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